

TPA-Based Characterisation of Solid-State Sensors Using a Tunable Femtosecond Pulsed Laser

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The University of Manchester, UK


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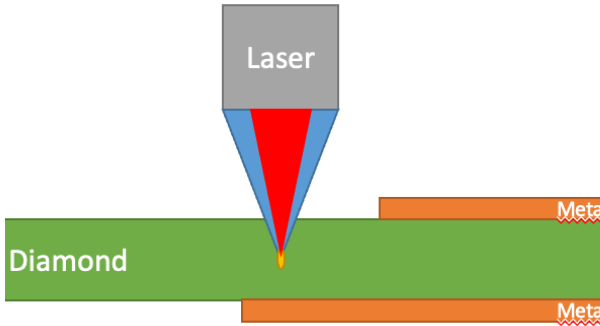
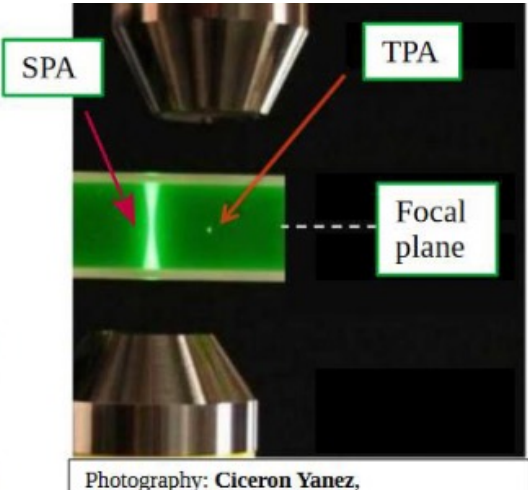
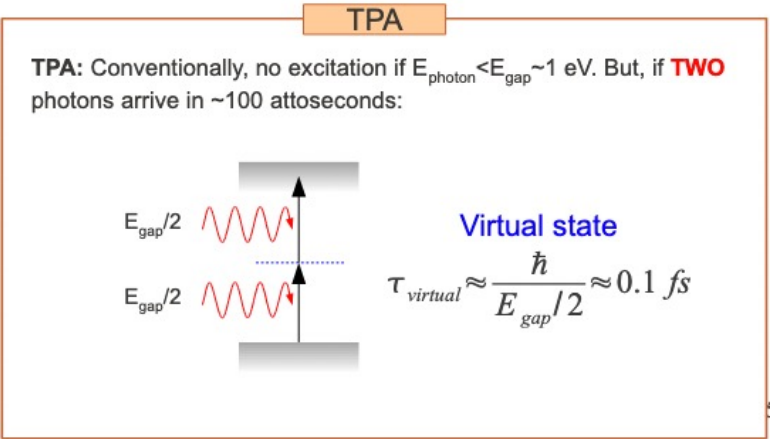
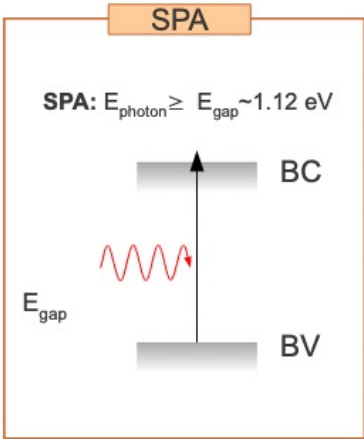


Outline

- **Introduction**
 - **Set-up**
 - **Measurements**
 - **Summary**
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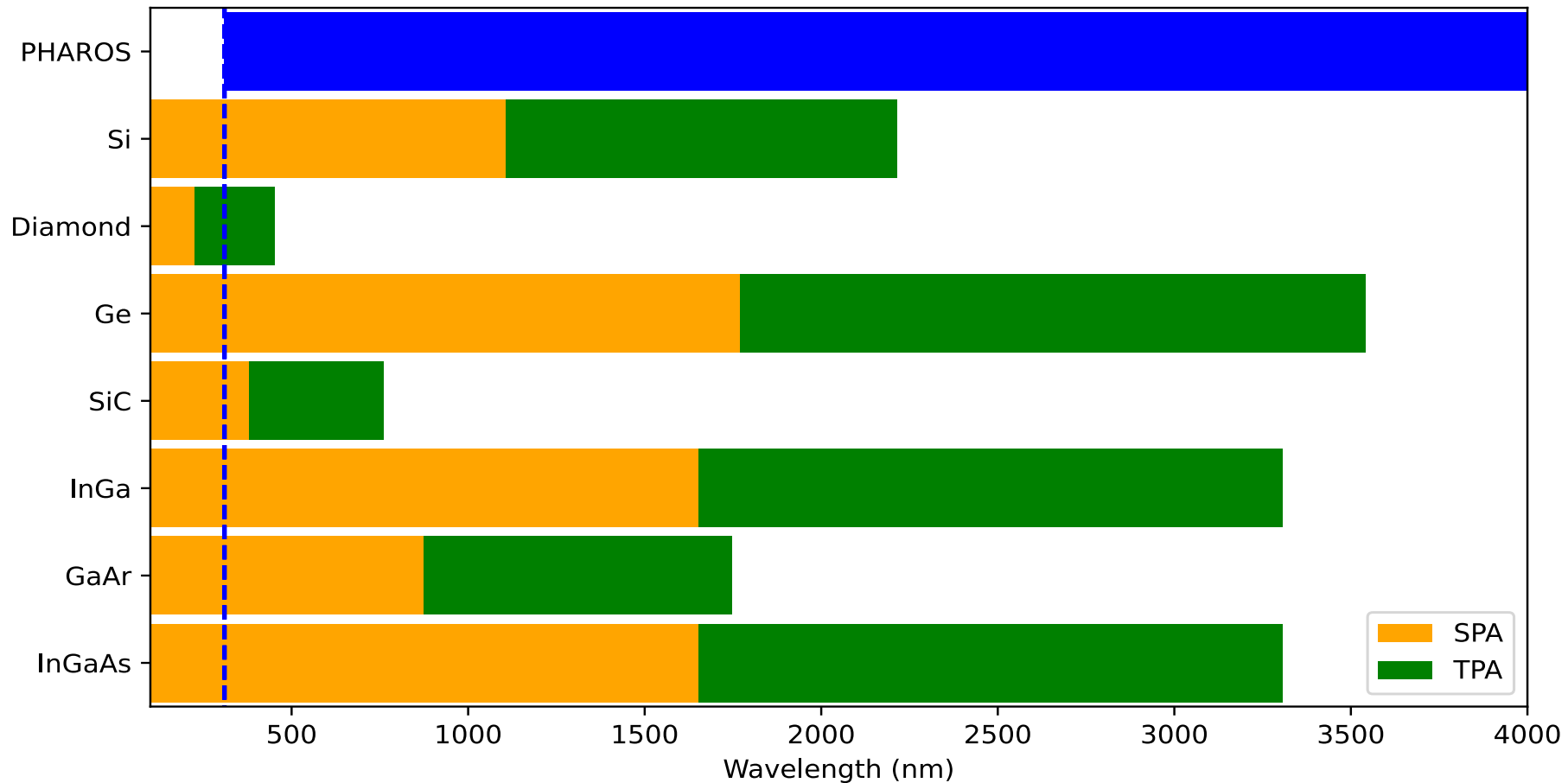
Introduction

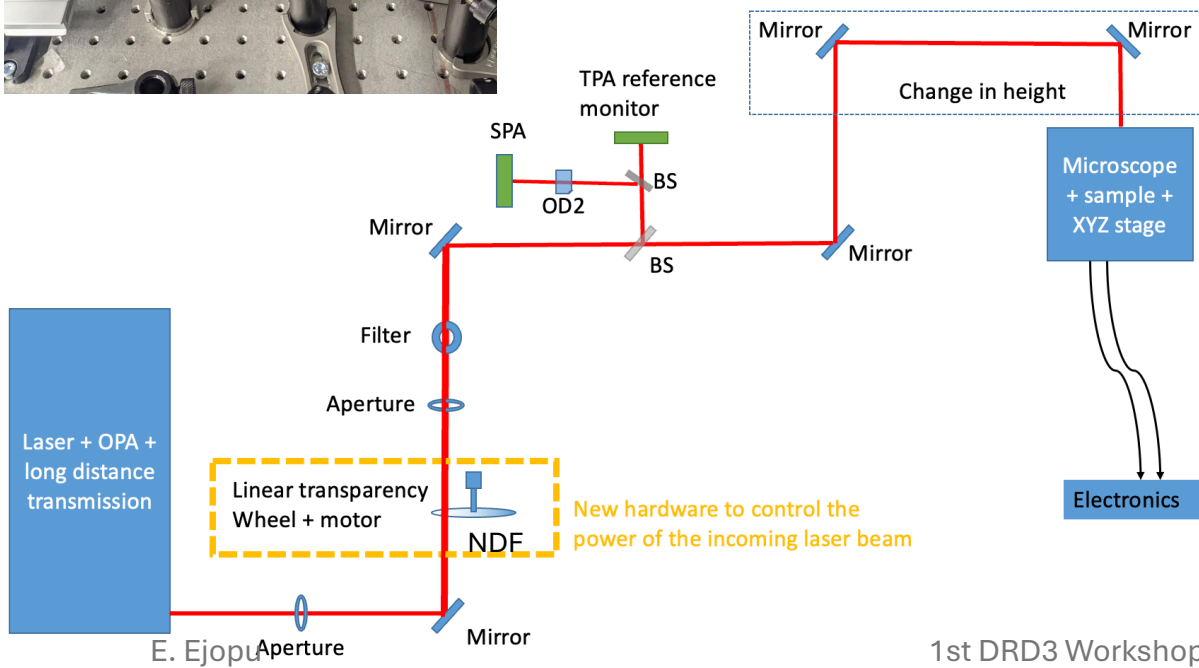
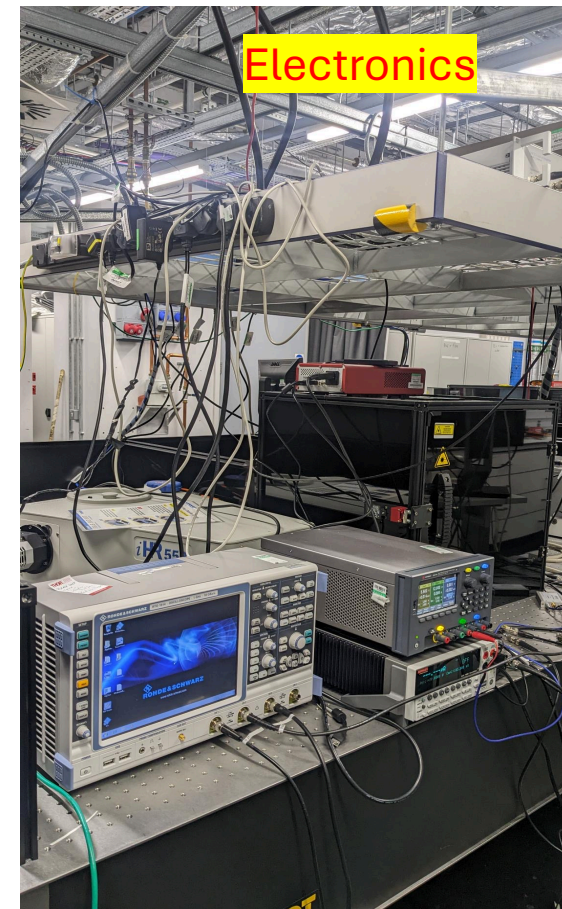
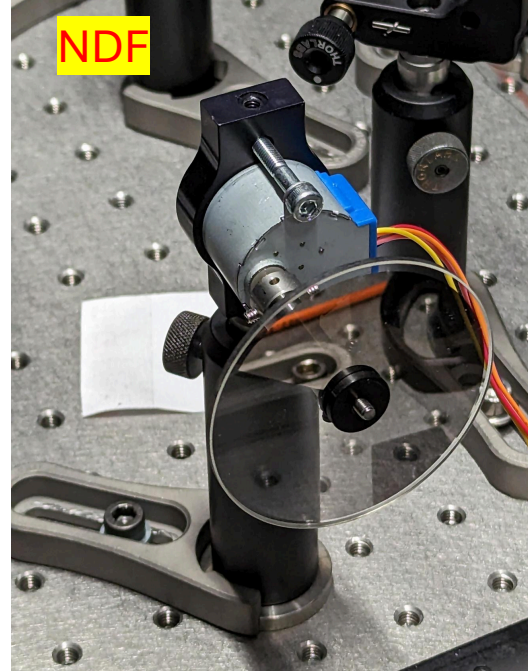
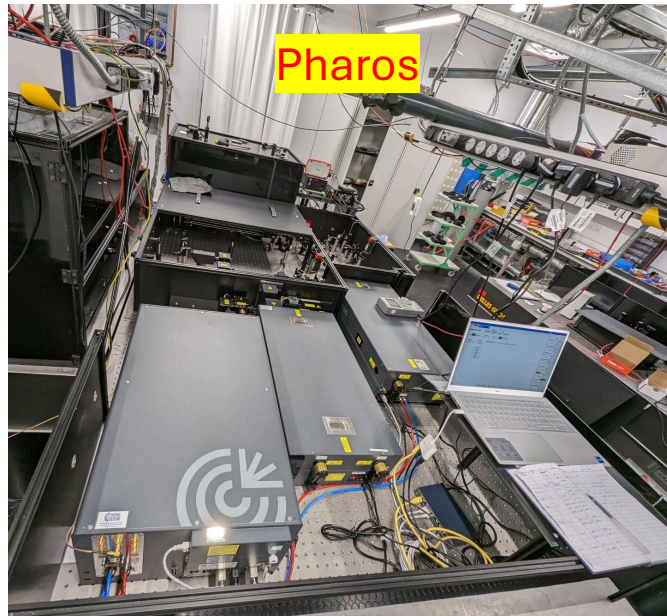
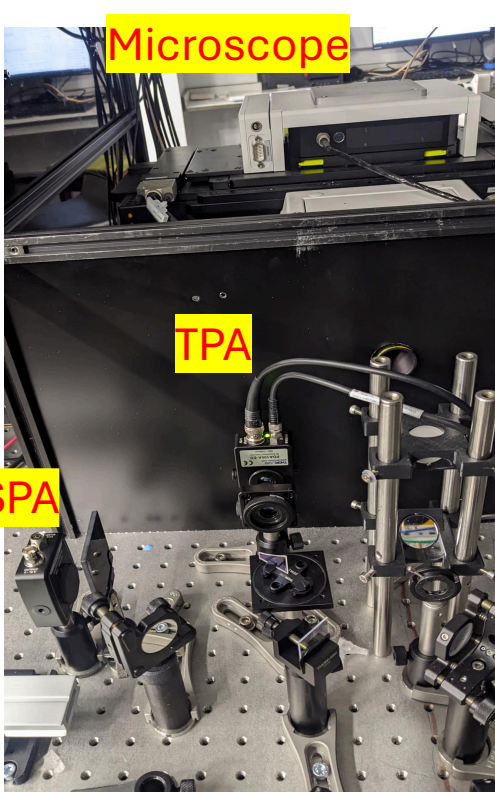
- Two-Photon Absorption (TPA) involves simultaneous absorption of two photons.
- Relies on photon density achieved by laser focus called “voxel” .
- No photons are absorbed out of the focus.
- Single beam is focused by a lens.



Laser Capability

- Pharos wavelength range is from 330 nm to 16000 nm.
- Tuned by the Optical Linear Parametric Amplifier (OPA).

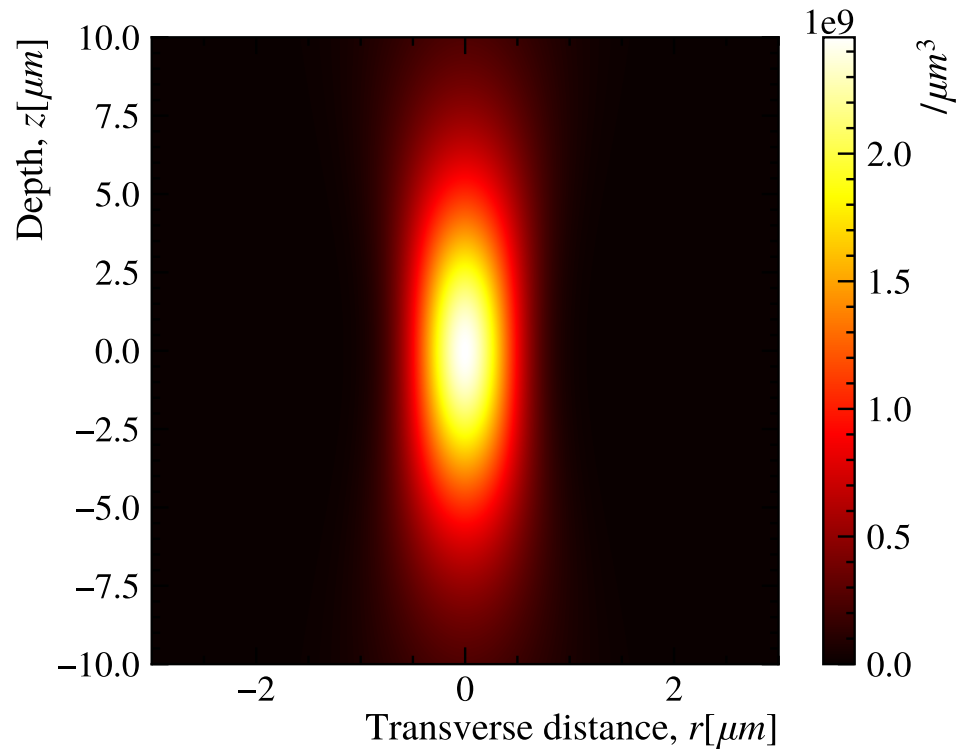




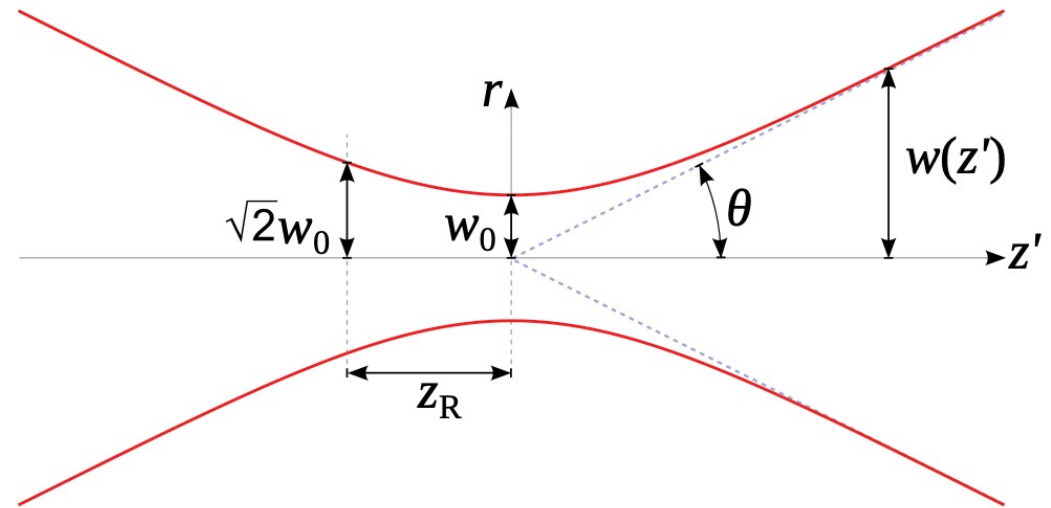
- PHAROS Femtosecond laser:
- Laser system: PHAROS Yb:Yag laser.
- Pulse duration (160 fs).
- Wavelength range from 330 nm to 16000 nm (3.757 eV to 0.077 eV).
- For Si as the DUT;
- Silicon sensor as reference monitor for TPA.
- And Ge sensor –SPA.
- Using an CIVIDEC C2 amplifier of 2 GHz.

Expected charge carrier density

- Determination of expected amount of charge carrier density.
- Based on the properties of the lens (NA 0.5, 20X) we expect the following voxel shape.
- Parameters: $\lambda = 1550 \text{ nm}$, $\tau = 160 \times 10^{-15} \text{ s}$, $\beta_2 = 1.5 \text{ cm/GW}$, $f = 10 \text{ kHz}$, $E_p = 350 \text{ pJ}$.

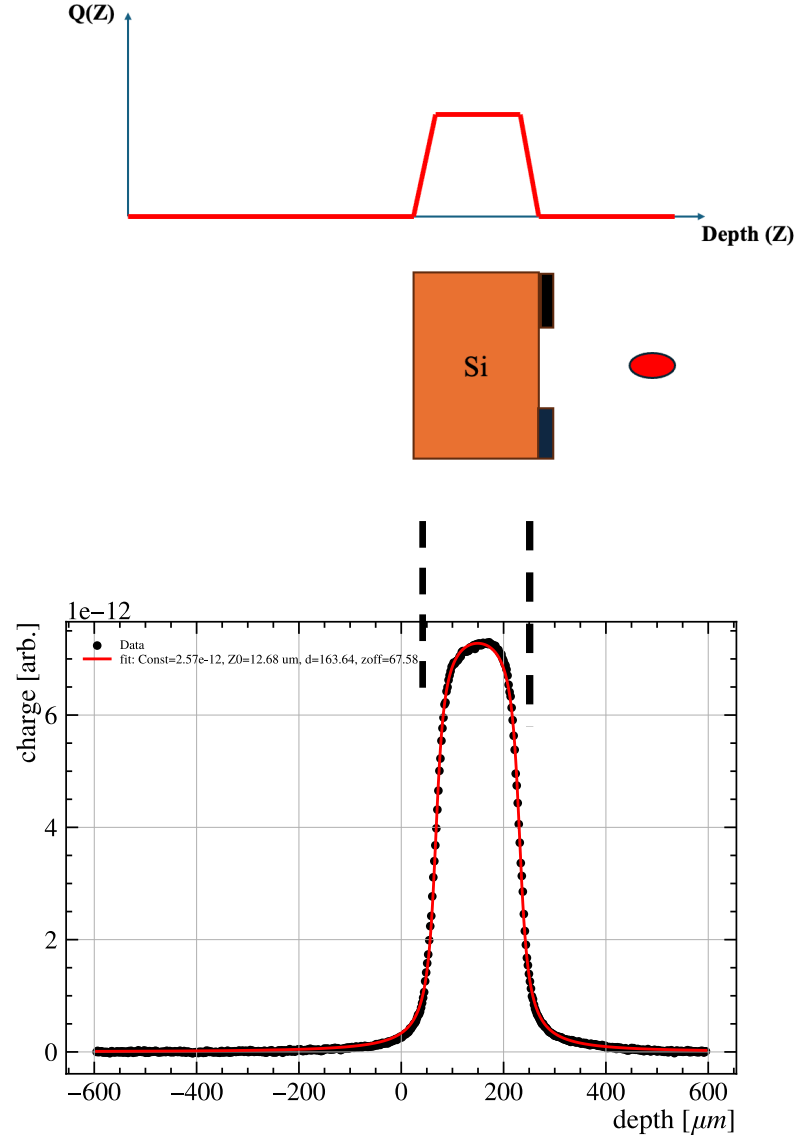


$$n_{tpa}(r, z) = \frac{E_p^2 \beta_2 4 \ln 2}{\tau \hbar \omega \pi^{\frac{5}{2}} w^4(z) \sqrt{\ln 4}} \exp\left[-\frac{4r^2}{w^2(z)}\right].$$



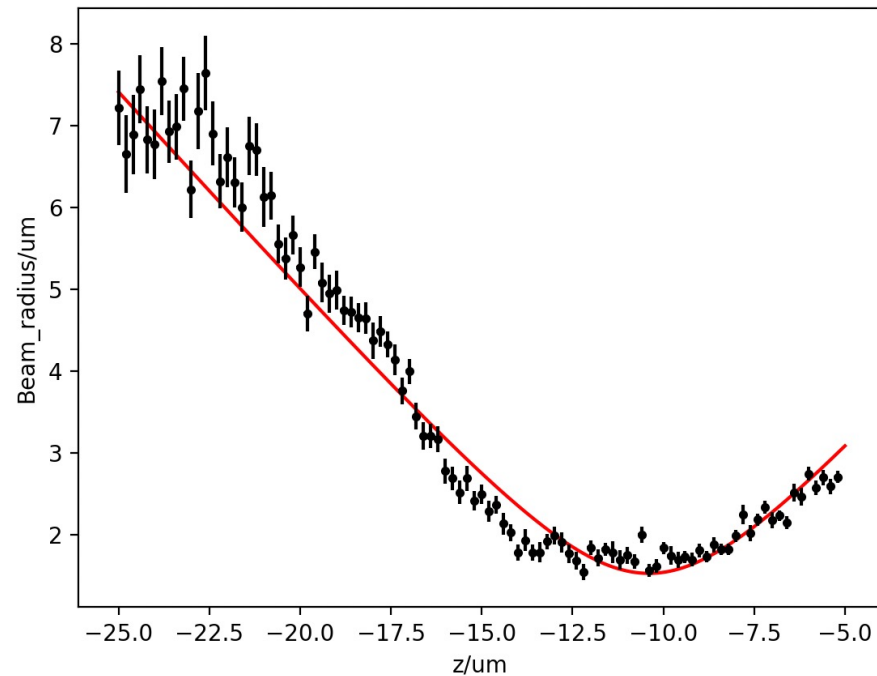
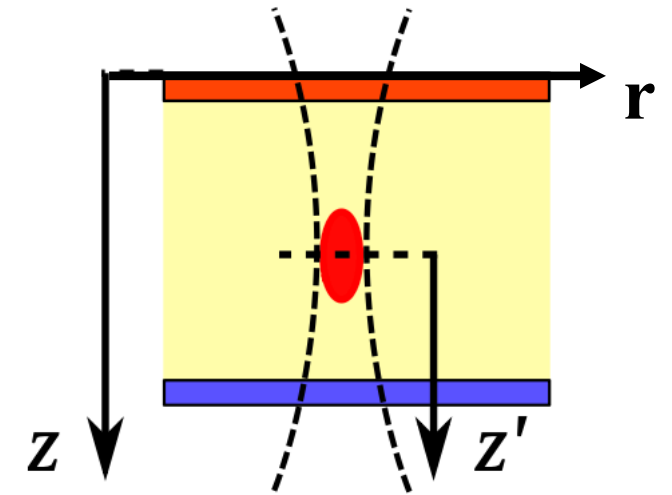
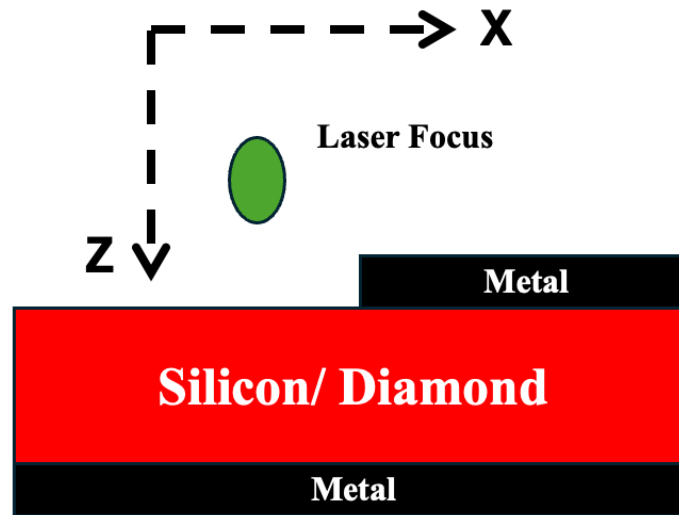
Silicon Diode Measurements

- Signal shape throughout the device depth.
- Charge distribution vs Depth well described by model.



Silicon Diode Measurements

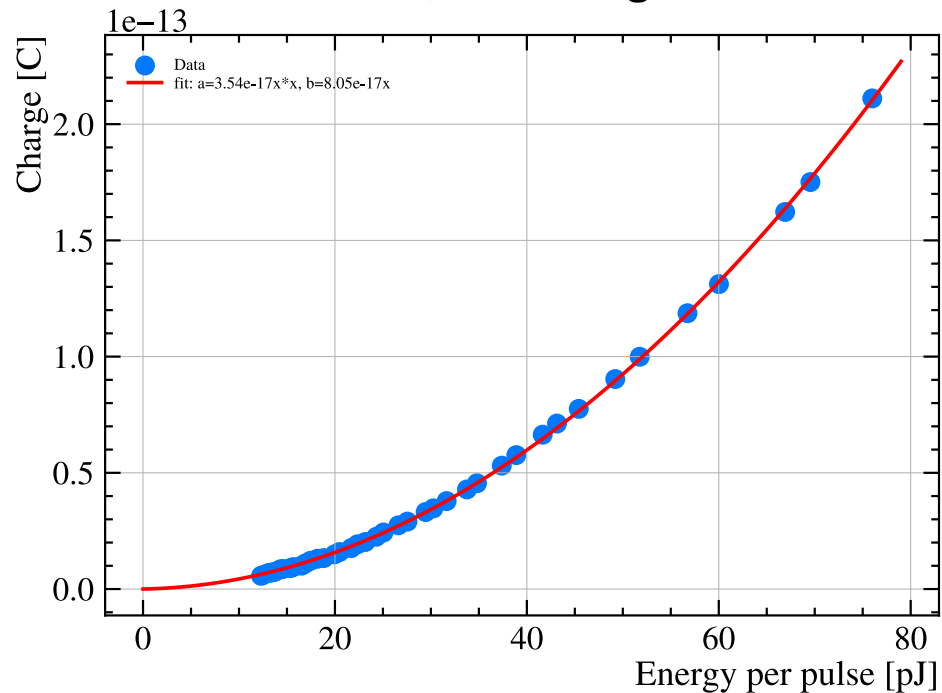
- Spatial resolution defined by the voxel.
- Knife edge scan.
- Voxel was found to be **10.4 μm** by **1.5 μm** .



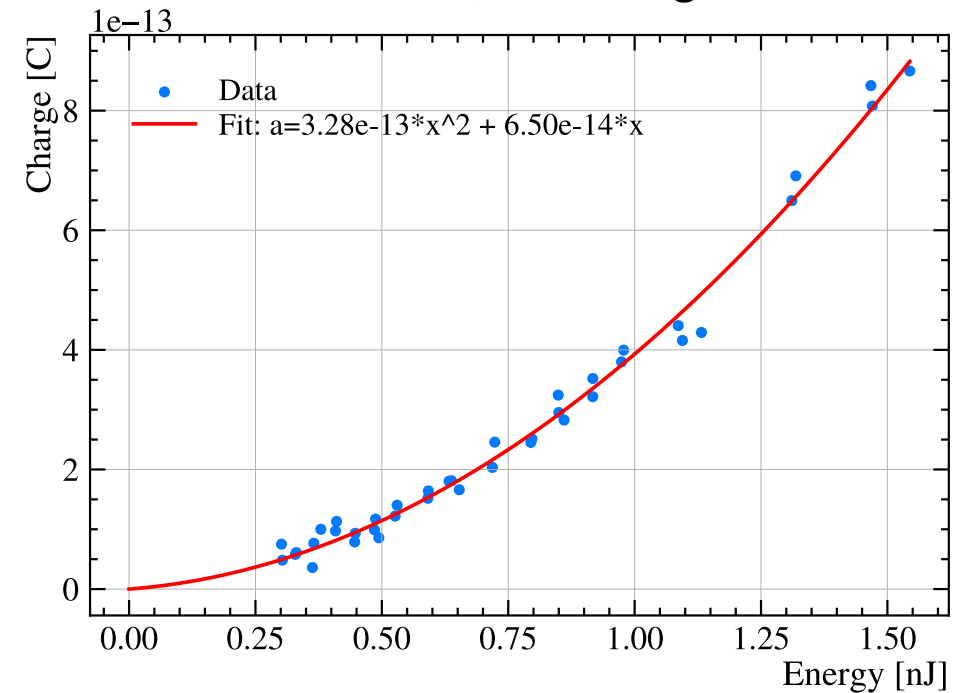
Measurements

- TPA confirmed in silicon (left) and diamond (right) as seen from the quadratic dependence and depth scan.
- Ionization density is proportional to the photon intensity squared.

Silicon, Wavelength = 1550 nm

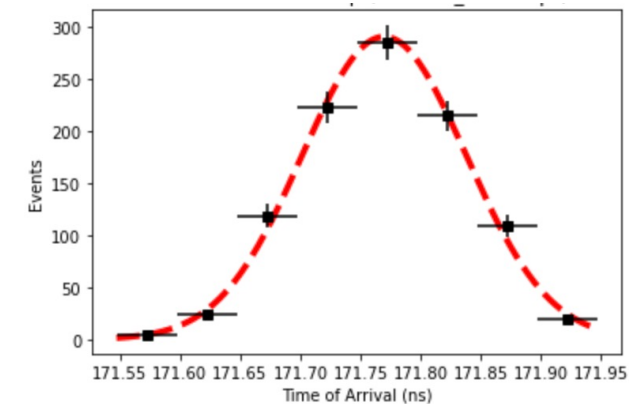
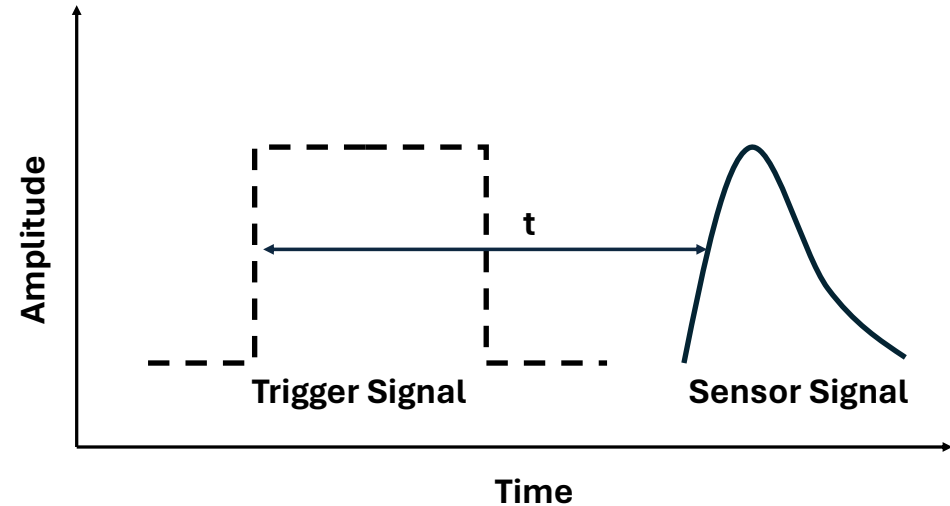


Diamond, Wavelength = 405 nm



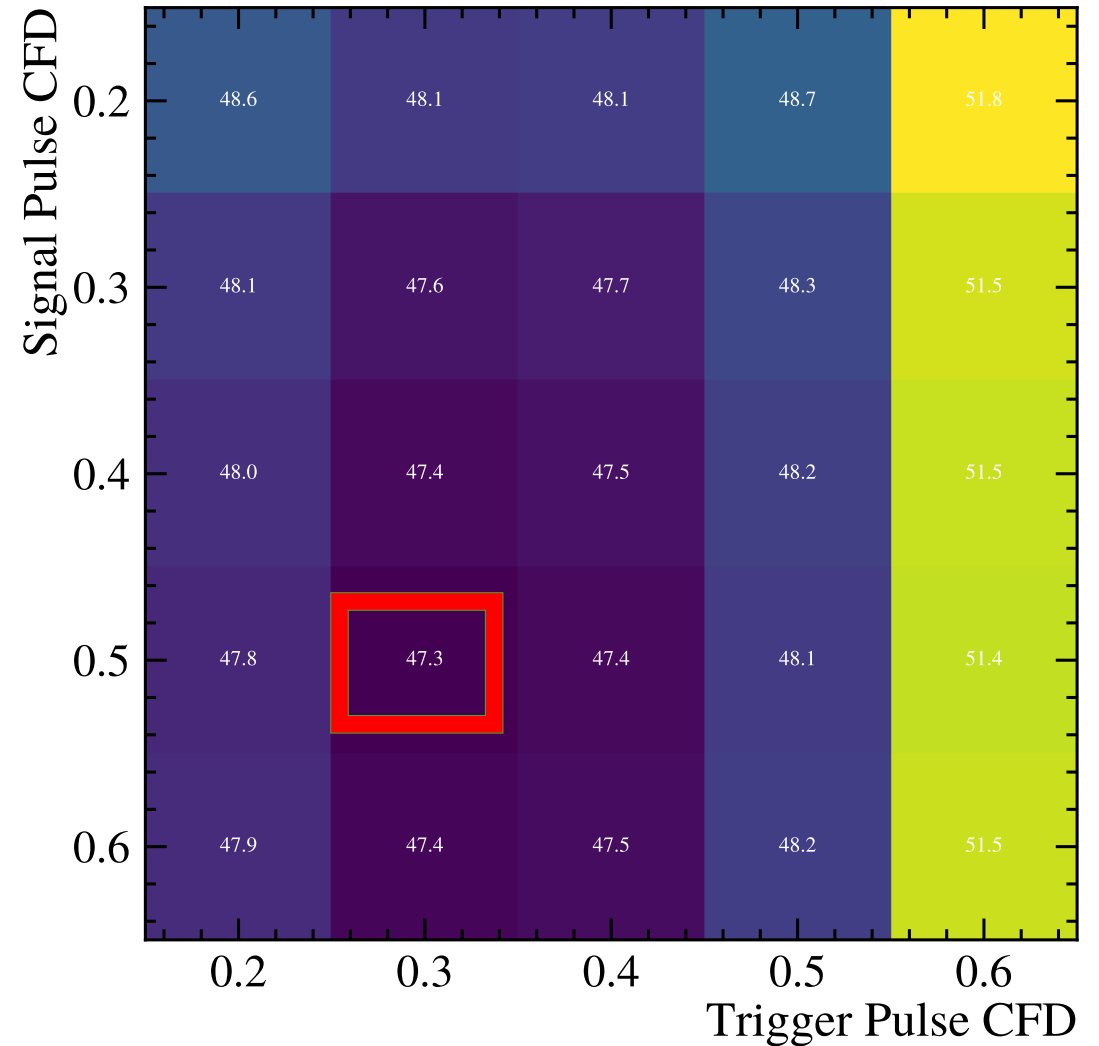
Time Resolution Measurement

- Obtaining multiple waveforms (1000) with no averaging.
- Constant Fraction Discriminator (CFD).
- Two methods used:
- Method 1: **Laser Trigger.**
 - The arrival time difference with respect to the trigger are determined at a fixed CFD.
 - The standard deviation of the difference gives the time resolution.



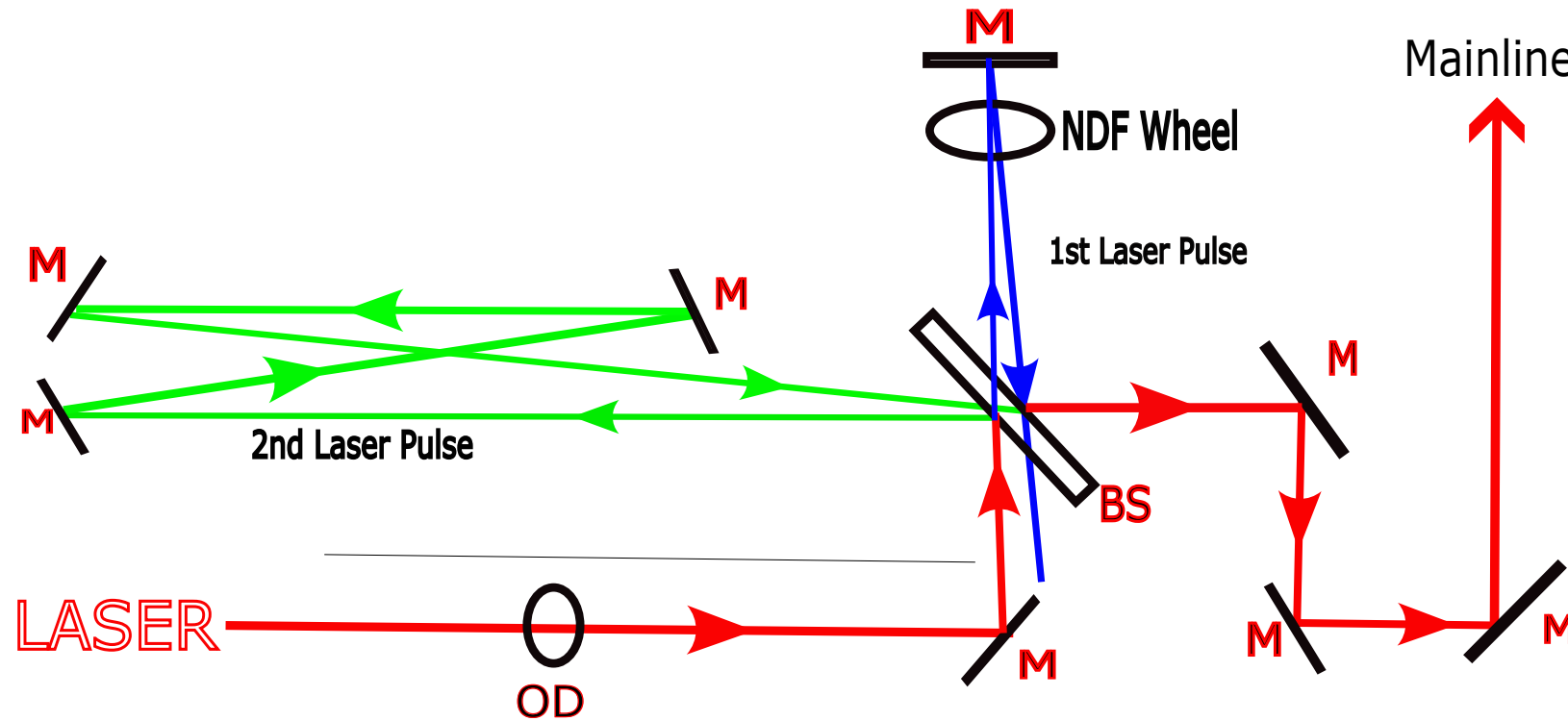
Timing...

- Time resolution for each combination of the trigger and signal thresholds were calculated.
- For LGADs, constant fraction discriminator + linear interpolation algorithm: **47.3 ps**.
- Pharos trigger time resolution is 20 ps with room for improvement.



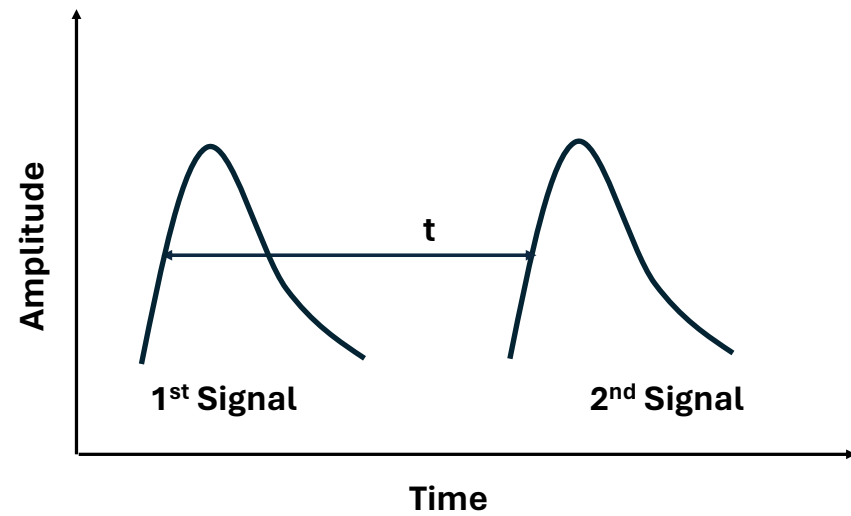
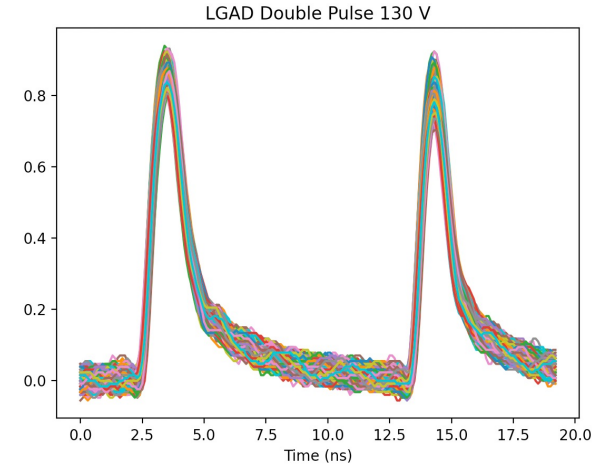
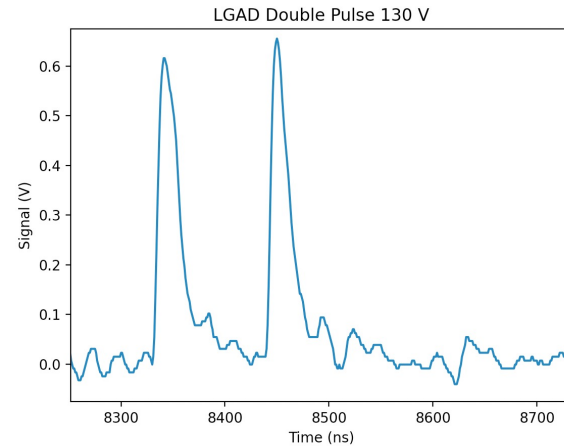
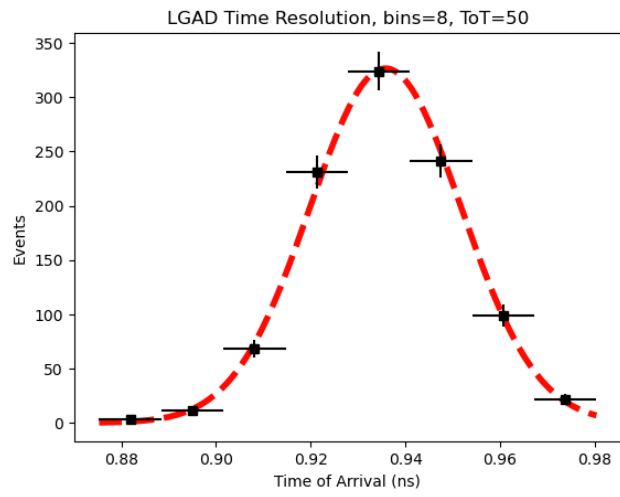
Double Pulse Method

By splitting the laser beam using the set-up shown.



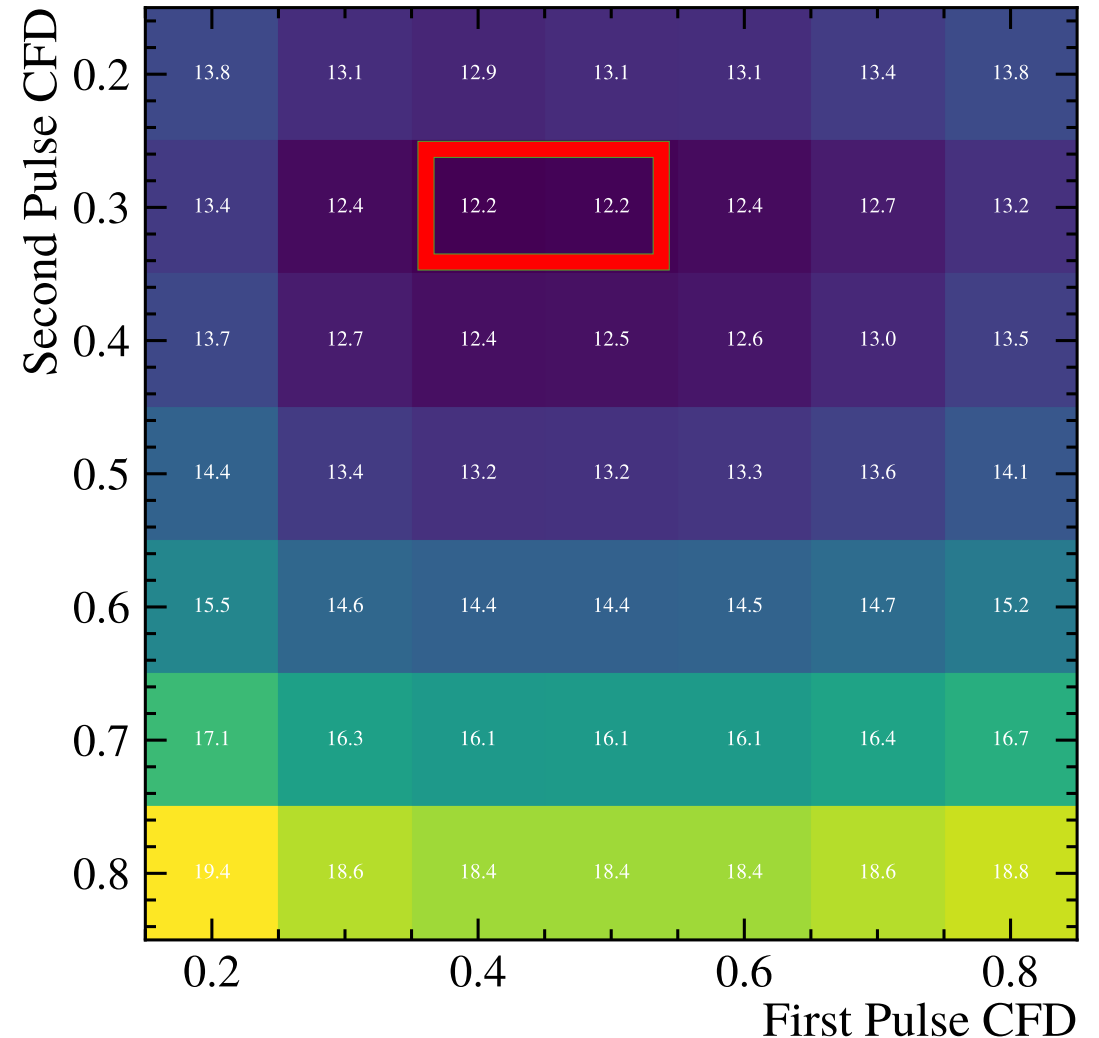
Timing...

- The arrival time difference between the 1st and 2nd pulse are determined.
- The standard deviation of the difference gives the time resolution.



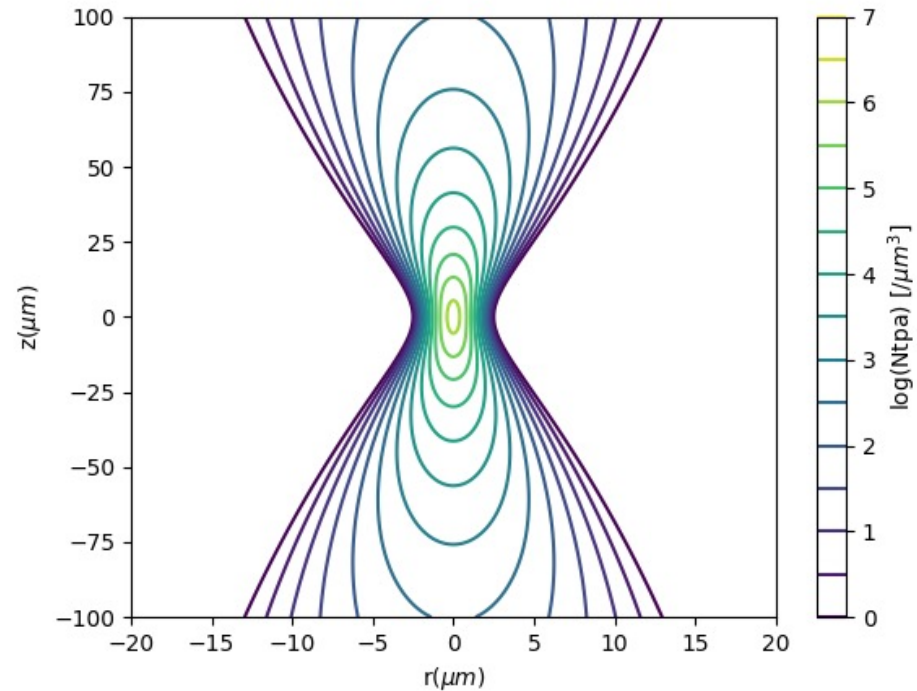
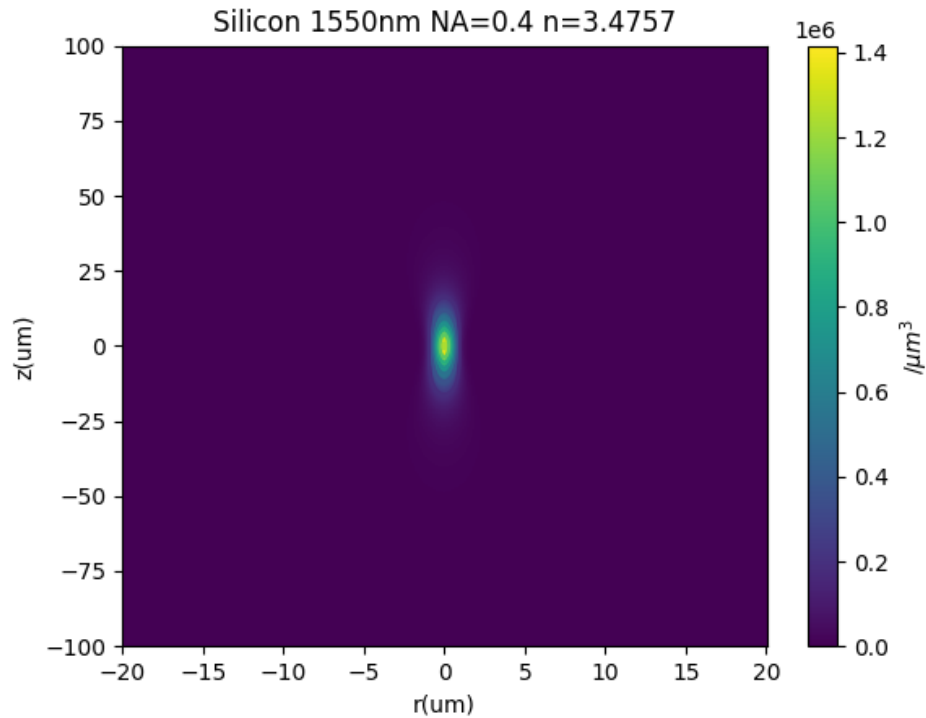
Time Resolution Mapping for different CFDs

- Bias voltage = 130 V
- LGAD: 3331_13 #5
- CFD method.
- 0.1 is 10%, 0.2 = 20% etc of signal.
- Horizontal- 1st pulse CFD and Vertical- 2nd pulse CFD.
- Best time resolution of **12.2 ps** at a CFD of (40%, 30%) & (50%, 30%) for 1st pulse and 2nd pulse respectively.
- **8.6 ps** intrinsic time resolution.



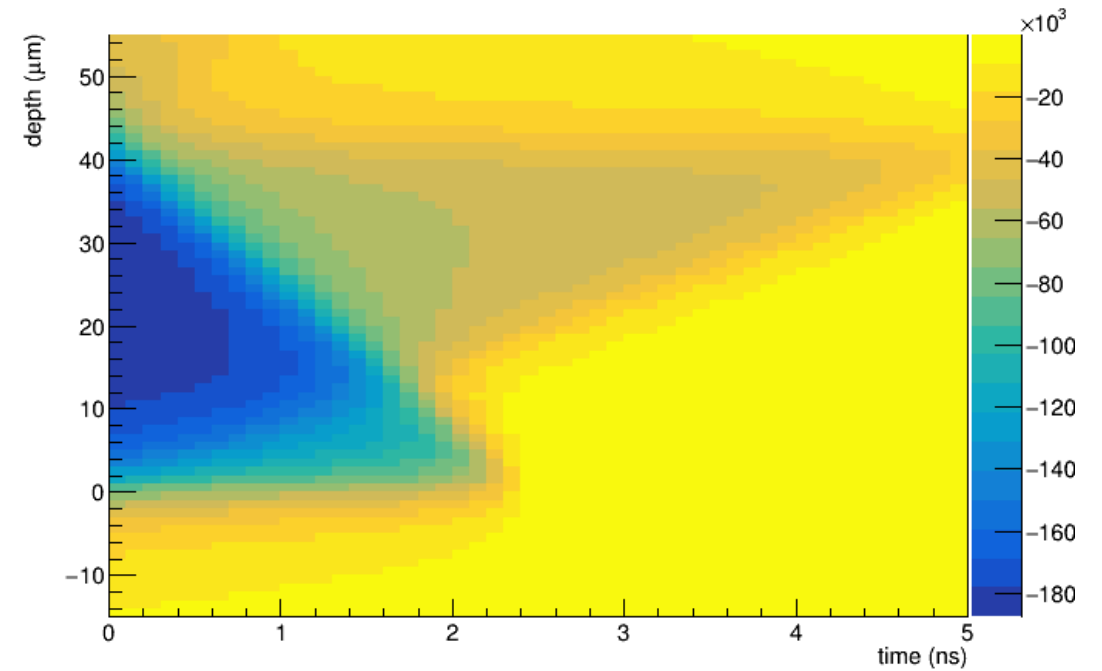
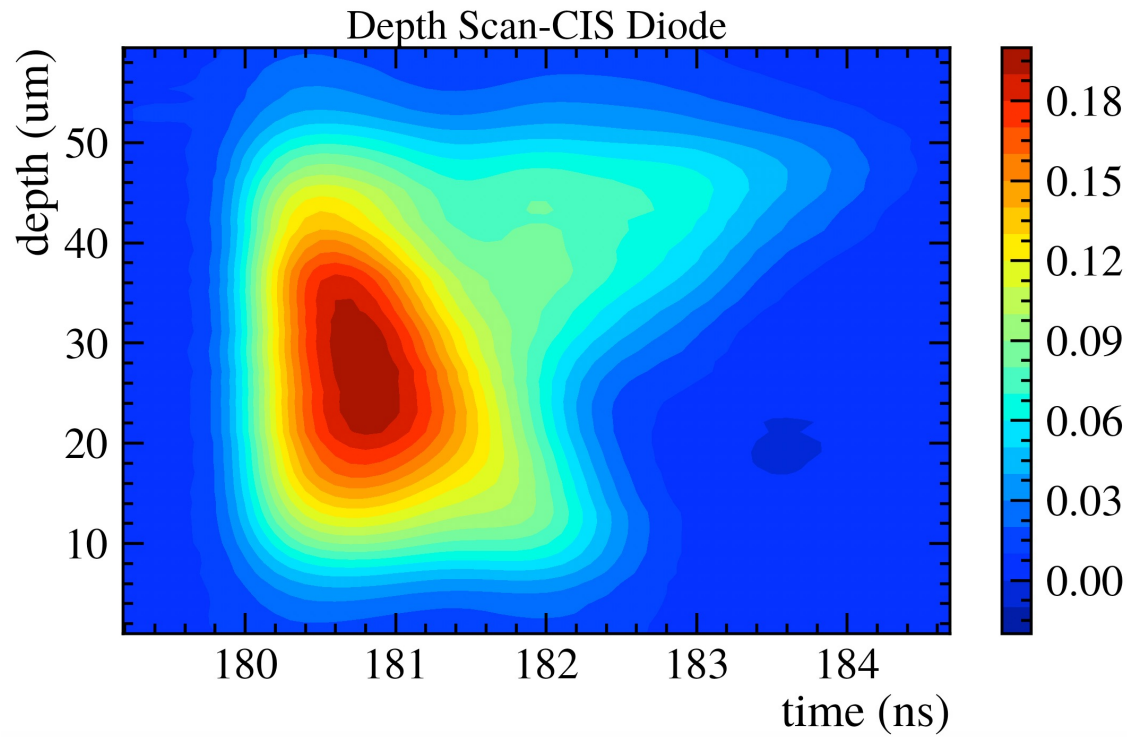
KDetSim Simulation

- The expected induced charge in a silicon device and the corresponding curve levels in logarithmic scale.
- Simulation parameters: wavelength =1550nm, $E_p = 0.1\text{nJ}$, $NA=0.37$ and $\tau = 160\text{fs}$.



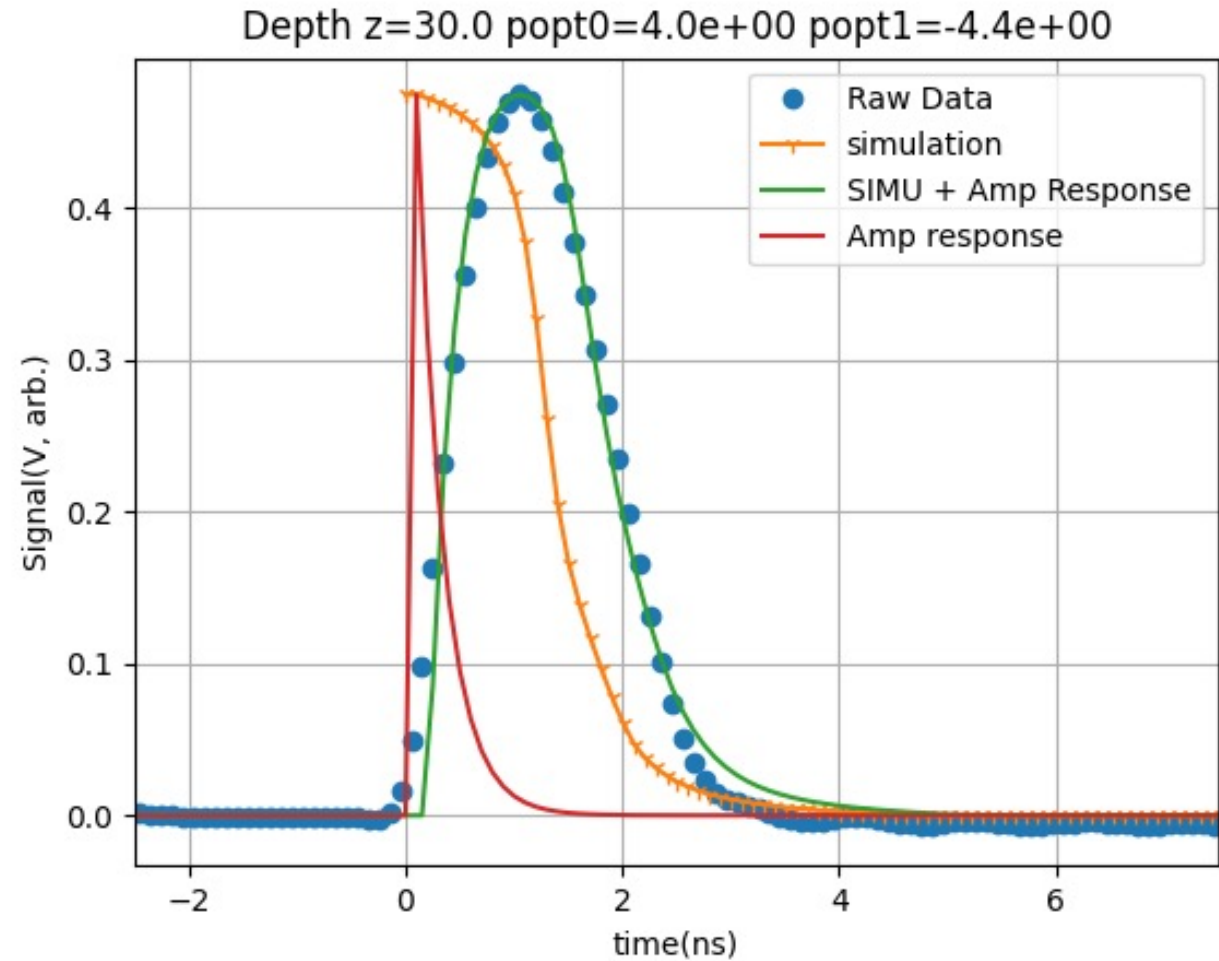
KDetSim

Comparison between experimental (left) and simulation (right) Depth-time scan of TPA signal using a diode.



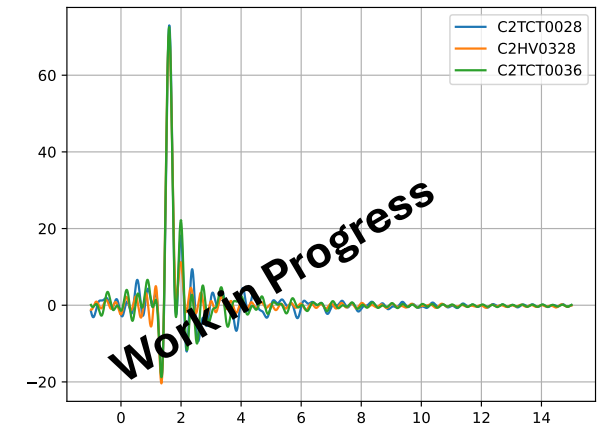
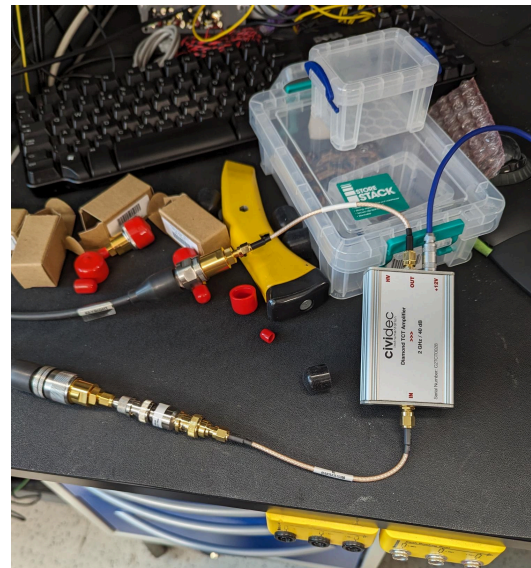
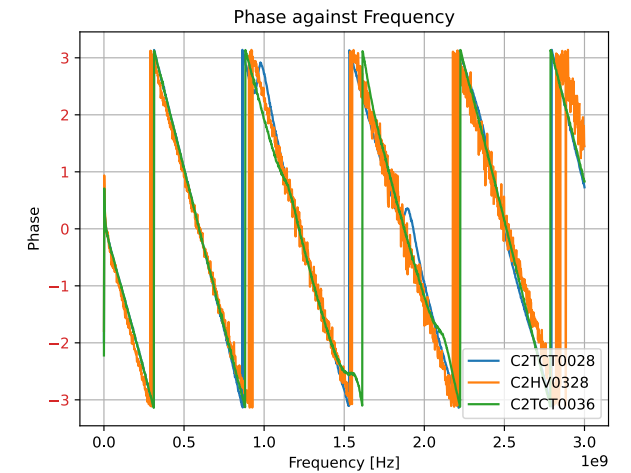
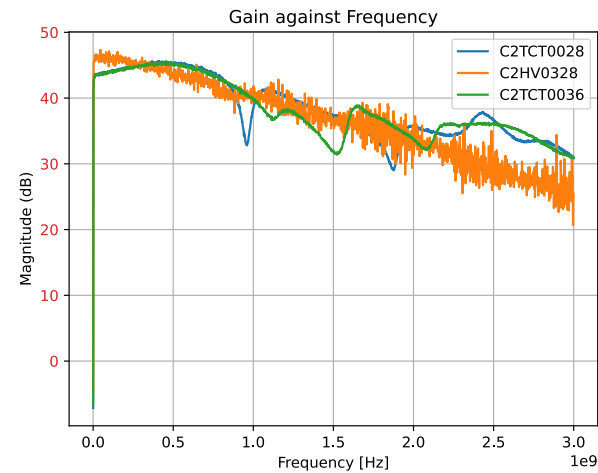
KDetSim

- Voxel is projected in 1D and used as input on KDetSim.
- KDetSim predictions as a function of depth at different depths at the device at the middle of the device ($z = 30\mu m$).

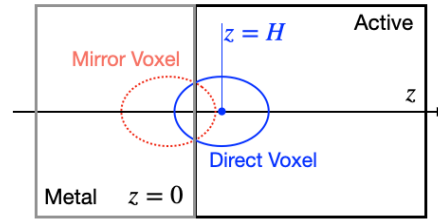


Simulation & Amplifier Modeling

- Amplifier response (below) is determined using a Network Analyzer (KEYSIGHT E5061B ENA Series, 5Hz – 3 GHz).
- Results used for simulation studies.



Reflection Model



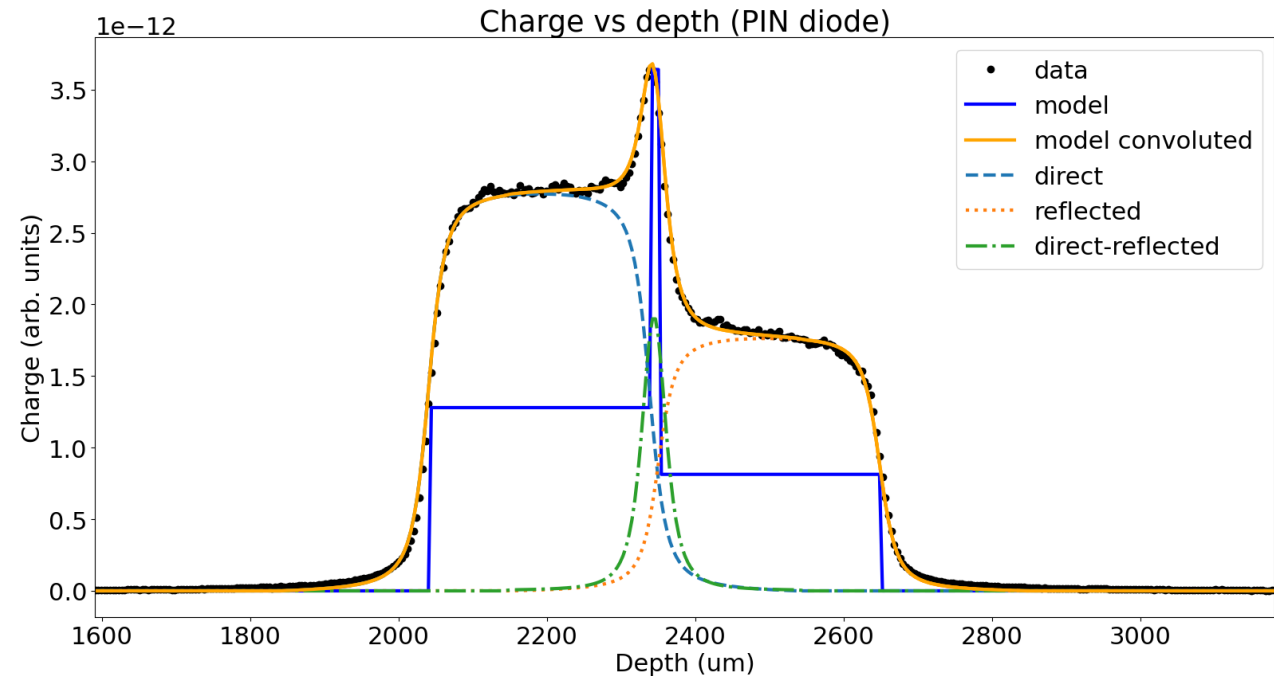
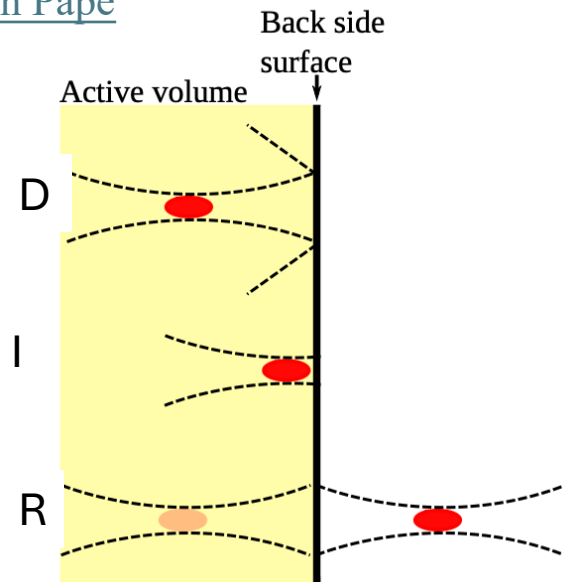
$$I_0 = I_D + I_R$$

$$n \propto I^2$$

$$n_{\text{TPA}} = n^D + n^R + n^I$$

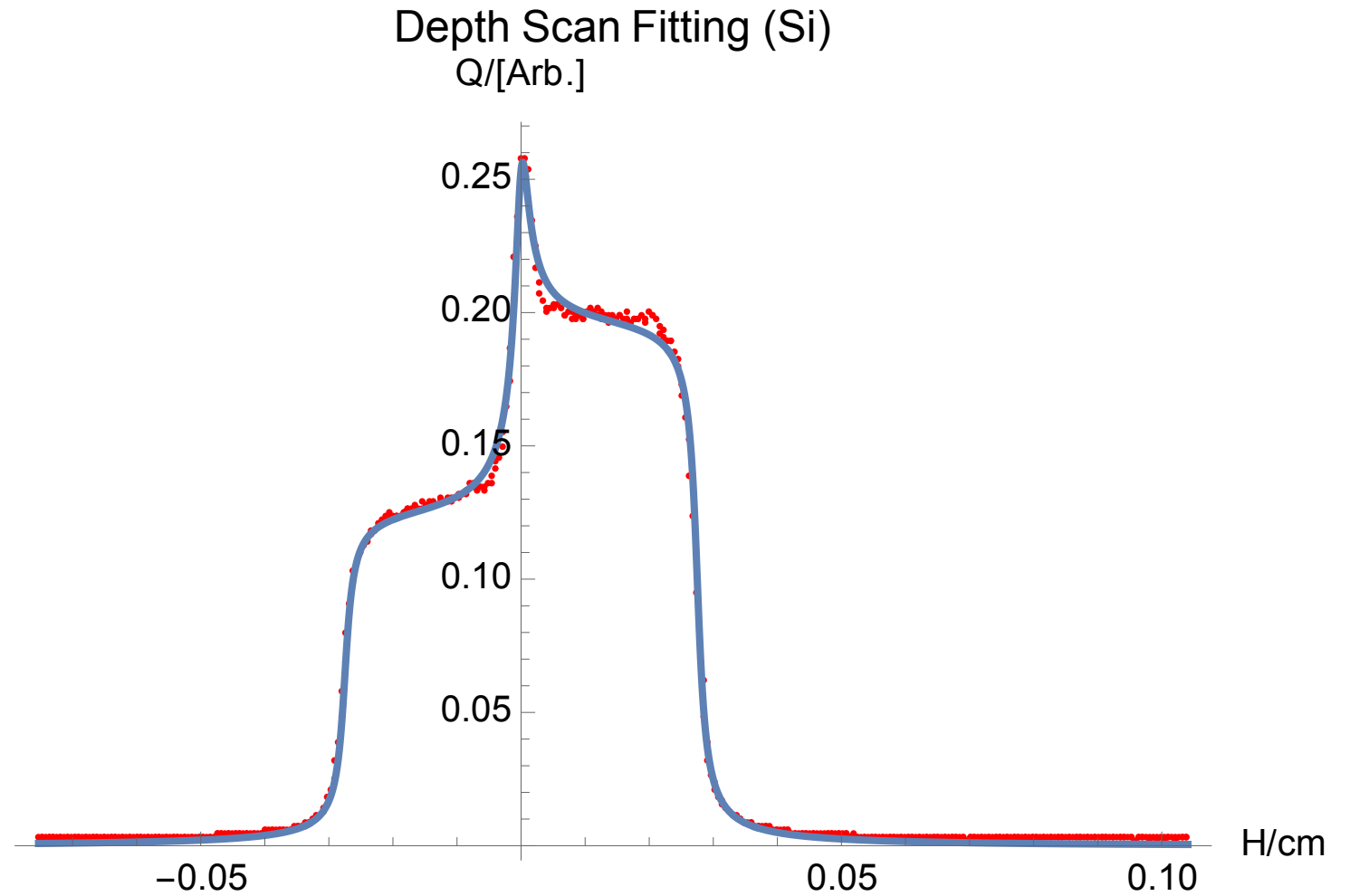
- To understand the voxel reflection.
- Convolute the reflected charge over z-axis.

Sebastian Pape



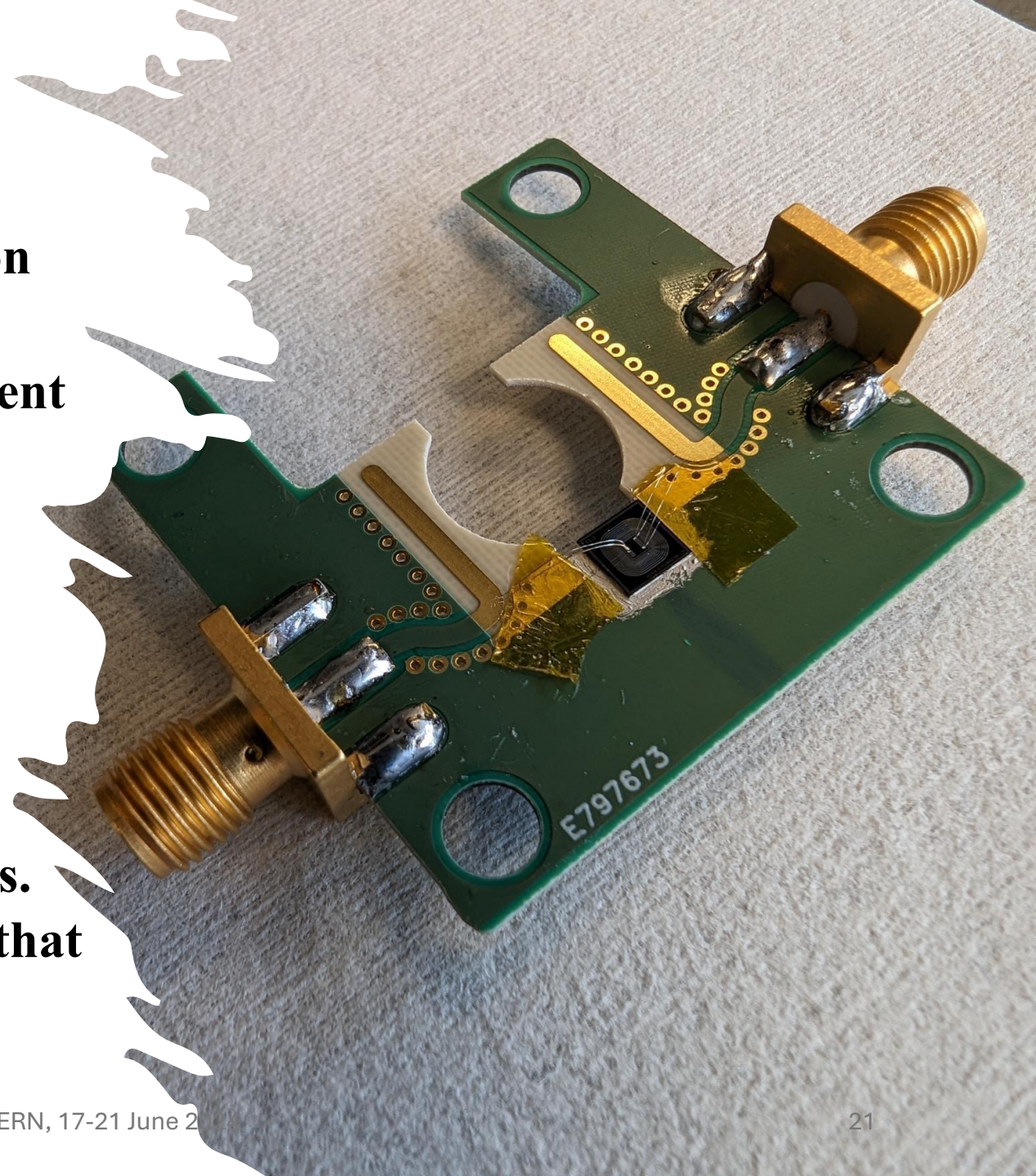
Reflection Model

- Comparison between fitted model and depth scan data for CNM Silicon sample ($275\ \mu\text{m}$ thickness).



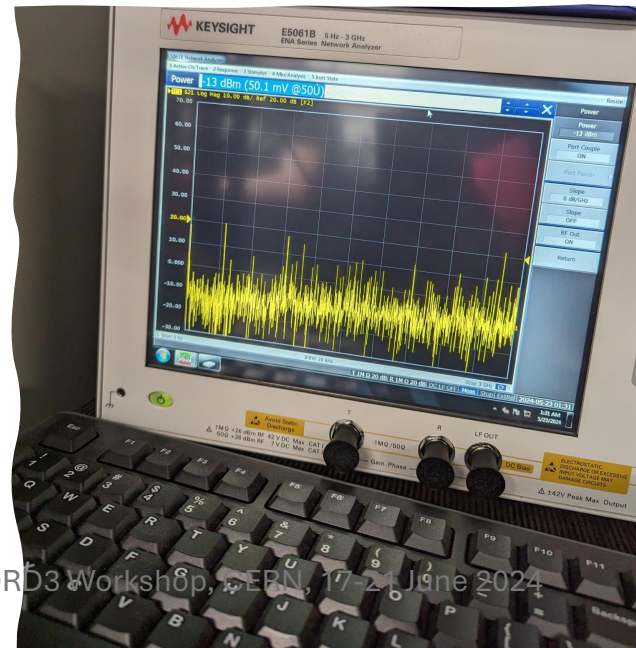
Summary

- **Performed TPA characterisation for Silicon diodes, LGADs and Diamond.**
- **Measured time resolution using two different techniques.**
- **On going:**
 - **3D diamond characterisation.**
 - **Trench LGADs.**
 - **Optimization of simulation.**
- **Potential Improvements:**
 - **A cooling system for irradiated samples.**
 - **Additional sensor to measure photons that go through the sample.**



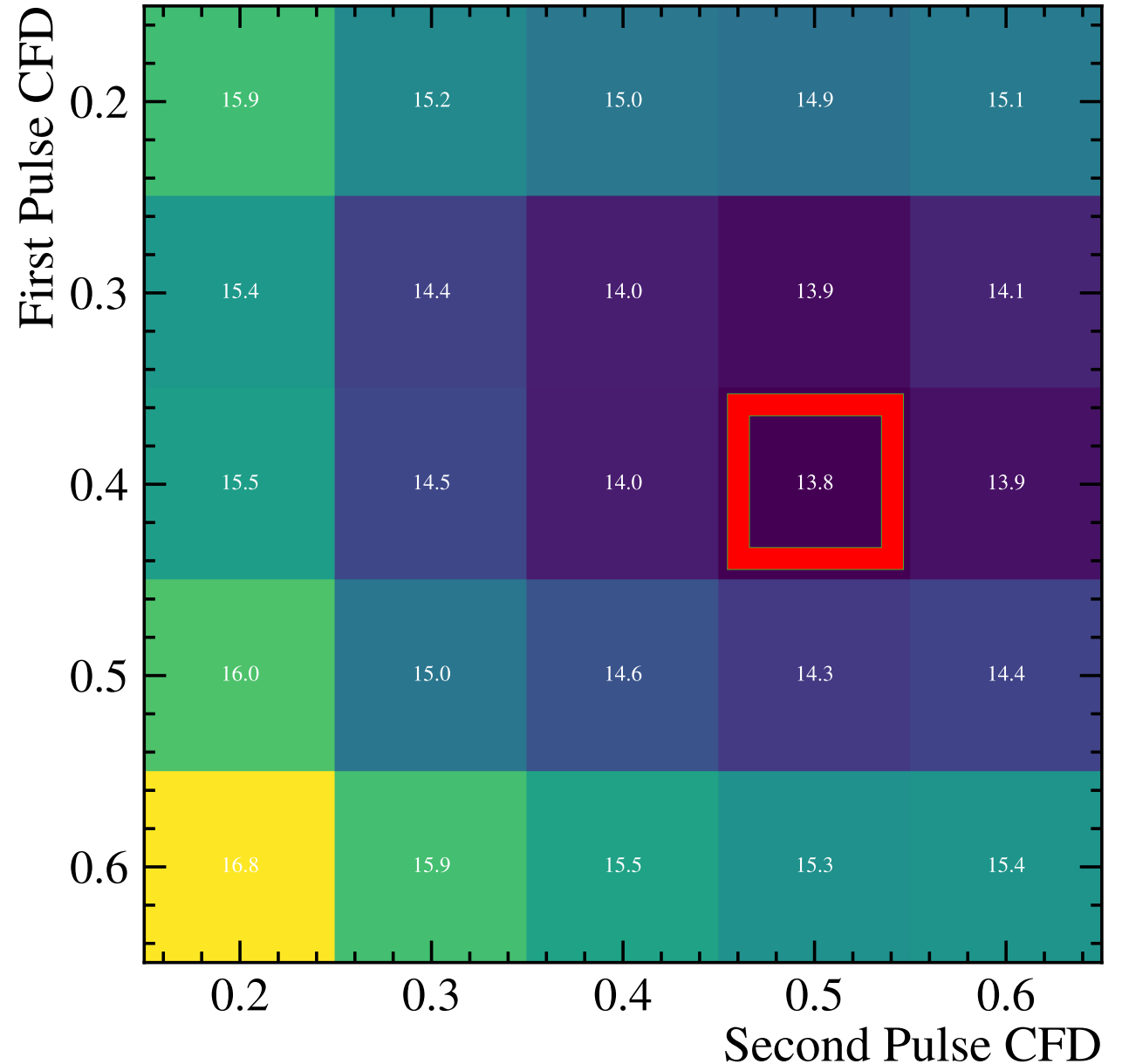
Back Up

- Amp modelling set-up.



Time Resolution Mapping for different CFDs

- Bias voltage = 100 V
- LGAD: 3331_13 #5
- CFD method.
- Horizontal- 1st pulse CFD and Vertical- 2nd pulse CFD.
- Best time resolution of **13.8 ps** at a CFD of (40%, 50%) for 1st pulse and 2nd pulse respectively.



Reflection Model

$$\begin{aligned}
 n_{\text{TPA}}(z, H, r) &= \frac{\beta_2}{2\hbar\omega} \int_{-\infty}^{\infty} dt I^2(z, r, t) \\
 &= \frac{\beta_2}{2\hbar\omega} \int_{-\infty}^{\infty} dt \left[I_D(z - H, r) e^{-\frac{4 \ln 2 r^2}{\tau^2}} + R I_D(-z - H, r) e^{-\frac{4 \ln 2 (r + \Delta r)^2}{\tau^2}} \right]^2 \\
 &= \frac{\beta_2 \tau}{4\hbar\omega} \sqrt{\frac{\pi}{2 \ln 2}} I_D^2(z - H, r) + \frac{\beta_2 R^2 \tau}{4\hbar\omega} \sqrt{\frac{\pi}{2 \ln 2}} I_D^2(z + H, r) \\
 &\quad + \frac{\beta_2 R \tau}{2\hbar\omega} \sqrt{\frac{\pi}{2 \ln 2}} I_D(z + H, r) I_D(z - H, r) e^{-\frac{2 \ln 2 (\Delta r)^2}{\tau^2}},
 \end{aligned}$$

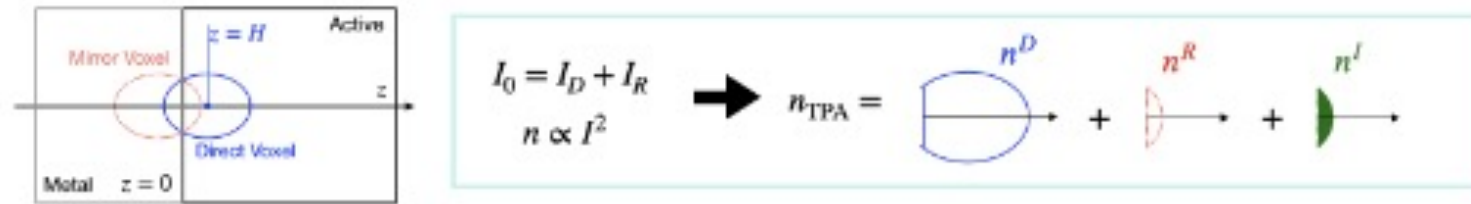


Figure 14: Schematic plot of two-voxel model. Any direct voxel centered at $z = H$ must have a corresponding mirror voxel at $z = -H$. Plane $z = 0$ is defined as the bottom plane of the sample.